Product Change Notification (PCN): 23151000 - Apalis Heatsink Type 0 V1.0A

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Known Hardware Issue — Apalis Heatsink Type 0 V1.0A (23151000)

A confirmed hardware issue (Errata HAR-13573) affects the Type 0 V1.0A heatsink. The Thermal Interface Material (TIM) has excessive hardness, which can cause PCB bending on Apalis iMX8 family modules when the heatsink is mounted. This may lead to solder joint fatigue, intermittent electrical connections, or premature field failures — especially under thermal cycling or mechanical stress.

Action required: Customers using V1.0A (23151000) must transition to V1.0B (23151001), in which the issue is resolved. Supply of V1.0A has been discontinued.

1. Affected Products

End of Life Product		Replacement Product	
Part Number	**Product Name**	**Part Number**	**Product Name**
23151000	Apalis Heatsink Type 0 V1.0A KNOWN ISSUE	23151001	Apalis Heatsink Type 0 V1.0B

2. Product Phase-in / Phase-out Schedule

End of Life Product		Replacement Product	
Part Number	**Estimated Schedule**	**Part Number**	**Estimated Schedule**
23151000 ✕ DO NOT ORDER	No LTB/LTS [1]	23151001	Sample Availability: Now Volume: Sept 2026

[1] Due to the confirmed issue in V1.0A (Errata HAR-13573), Toradex has stopped supply immediately to protect customers from reliability risks. No last-time buy or last-time ship windows are offered for this version.

Alternative heatsinks for Apalis iMX8: To continue supporting customers during the transition, Toradex is extending the LTB/LTS dates of the previously released Apalis Heatsink versions (Types 1, 3 and 4). For revision history and compatibility details, see Apalis Heatsink — Revision History and Apalis Heatsink Types, or contact your sales representative.

3. Description of Changes

Change #1: TIM (Thermal I Material) Material Change

- TIM material changed from **Bergquist TGP5000** to **Bergquist TGP3500ULM**
  - Resolves Errata HAR-13573

4. Customer Impact

Hardware

- **Impact — V1.0A users must take action.**

  The V1.0A heatsink (23151000) contains a confirmed issue: the TIM hardness is too high, which can bend the PCB on Apalis iMX8 modules when mounted. This creates risk of solder joint fatigue, intermittent electrical failures, or early field failures — particularly in thermally or mechanically demanding environments.

  The issue is resolved in V1.0B (23151001). Customers currently using V1.0A in production or late-stage design should transition immediately and assess any deployed units accordingly.

  Full details and workaround guidance: Errata HAR-13573

Software

- No software impact. This change is limited to the heatsink hardware — no changes to BSP, Toradex Easy Installer, or Torizon.

5. Contact

- Please contact Toradex if you have any questions.
- For commercial and sales questions, please contact shop@toradex.com
- For technical questions, please contact support@toradex.com